

Measurement of the Current Distribution of a Field Emission Cathode Array using a CMOS Camera and Comparison with the directly measured Current Values.

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1.) Essentials

2.) Intentions, Problems and Approach of Resolution

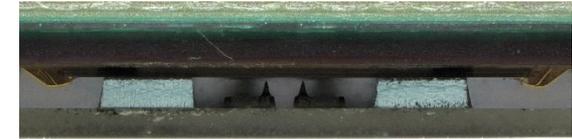
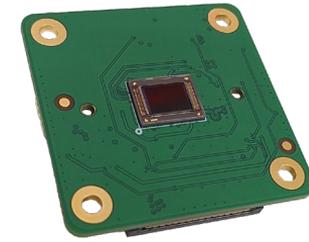
3.) Image Sensor Preparation and Modification

4.) Reliability of the sensor signal

5.) High FE Current Measurements

6.) Conclusion and Outlook

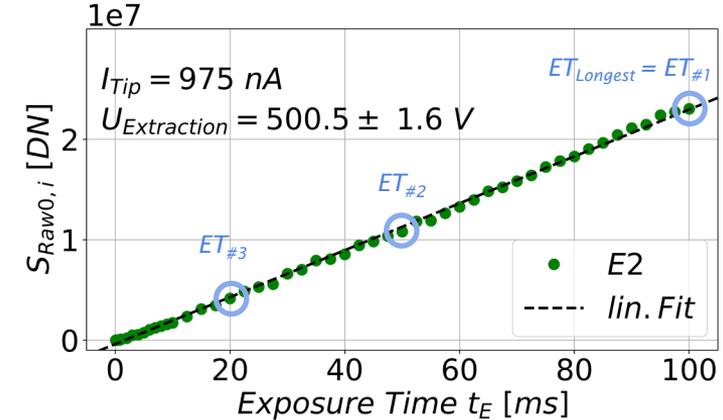
- Method was/is developed in collaboration with Ketek GmbH
 - Optical Image Sensor:
 - Camera-Model Raspberry Pi HQ-Camera
 - Image Sensor Sony IMX477
 - Resolution | Area 4056x3040 px² | ≈ 6.3x4.7 mm²
 - First demonstration by A. Schels [1] using an image sensor as commercially available
 - Assumed detection mechanism: XRay (Bremsstrahlung)
 - Camera signals are mapped as factorial shares on the electrically measured integral current of the FEA:



$$I_{OMap,Tip\ x} = I_{Total} \cdot F_{Tip\ x} \leftarrow F_{Tip\ x} = \frac{S_{Tip\ x} \cdot f_{Tip\ x}}{\sum_n S_{Tip\ n} \cdot f_{Tip\ x}}$$

Upscaling factors f

$$f_{Tip\ x} = \frac{ET_{Longest,Tip\ x}}{ET_{not\ overexposed,Tip\ x}} \begin{cases} = 1 & \text{if } n \\ > 1 & \text{if } o \end{cases}$$



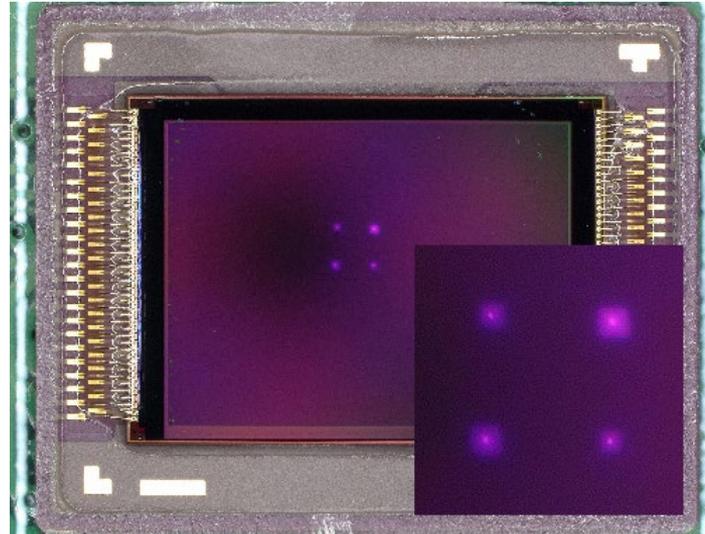
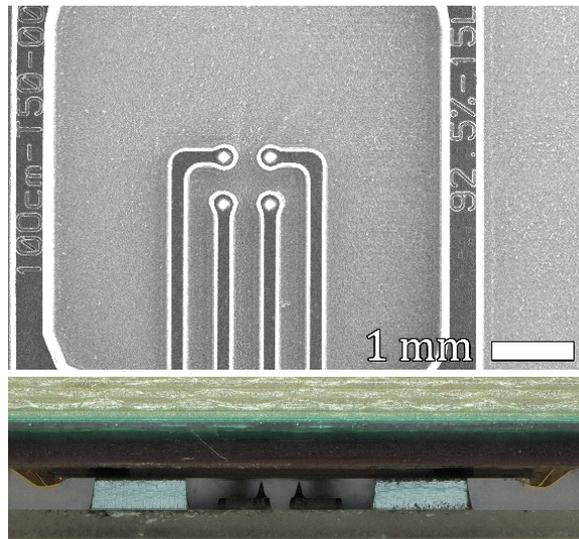
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Intention:

- Measuring higher currents in the microampere range
- Reliability of the optical sensor signal

Problem:

- Damaged areas of microlenses occurred already at a few 100 nA
- Microlenses made from carbon-compounds (bad- or non-conductive)



Damaged Image Sensor Surface

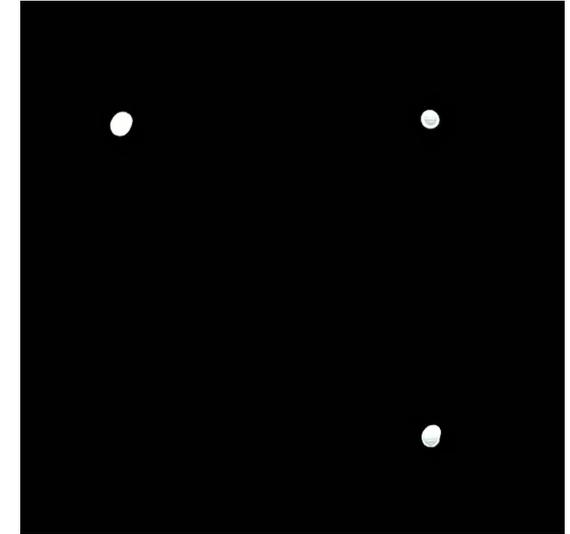


Image of a damaged sensor
(no voltage/field emission)

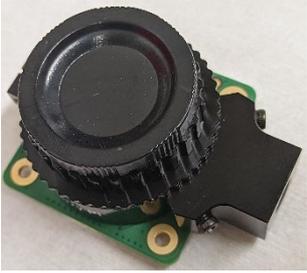
Solution:

- Metallic coating (Copper) of the sensor
 - Conductive surface and increased heat dissipation
 - Copper is a XRay-source target material
- n-Si FEA with 4 individually addressable tips [2] (direct comparison of electrical tip current and camera-signal)

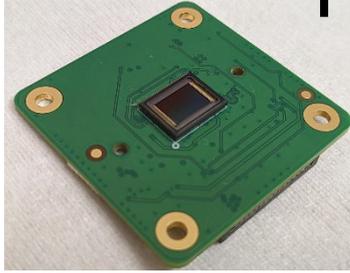
[2] R. Lawrowski, M. Hausladen, and R. Schreiner, "Individually Addressable Fully Integrated Field Emission Electron Source Fabricated by Laser Micromachining of Silicon," in 2020 33rd International Vacuum Nanoelectronics Conference (IVNC), Lyon, France: IEEE, Jul. 2020, pp. 1-2. doi: 10.1109/IVNC49440.2020.9203470.

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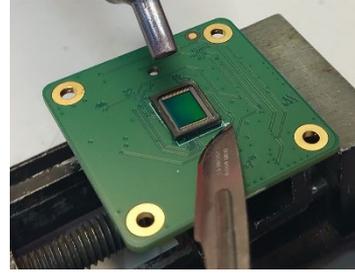
Cleaning step
(acetone & isopropanol
bath using ultrasonic)



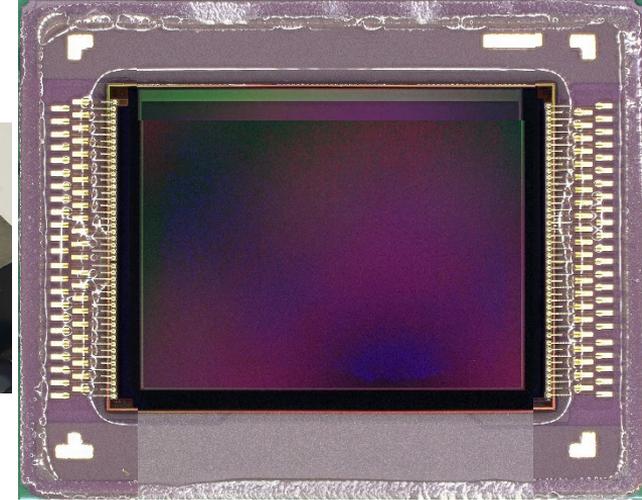
HQ-Camera as
commercially available



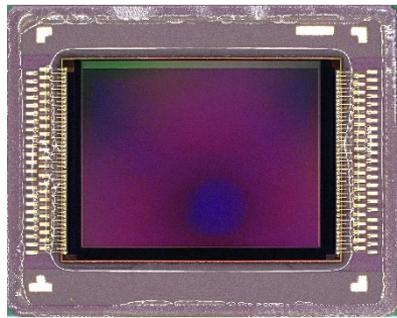
HQ-Camera with removed
C-Mount and sealing lip
(underneath the C-Mount)



Removal of
protection glass and
spacer frame



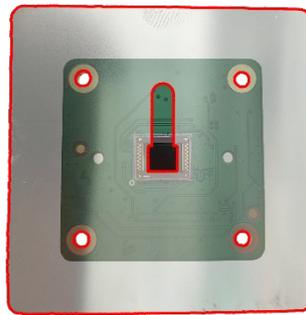
Blank unmodified sensor chip of the HQ-Camera
with secured bond-wires and ramps for the coating
process (UV-curing adhesive)



HQ-Camera with secured
bond-wires



Shadow-mask for the
coating process (laser-
cutted stainless steel
sheet)



Shadow-mask as semi-
transparent overlay on
the HQ-Cam PCB (red lines
indicate the mask
contour)

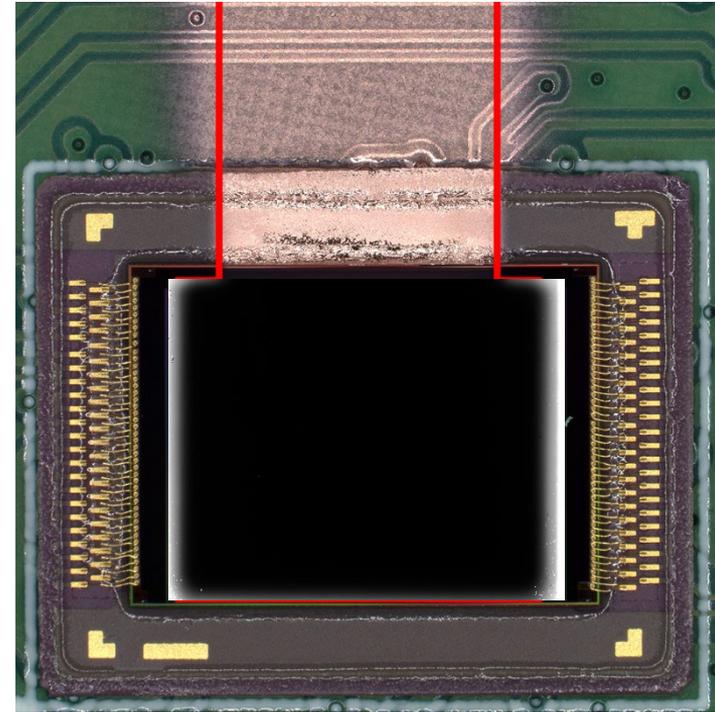
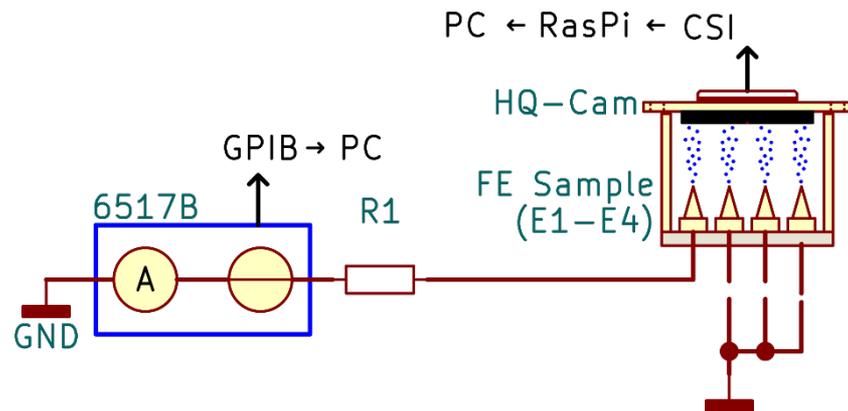
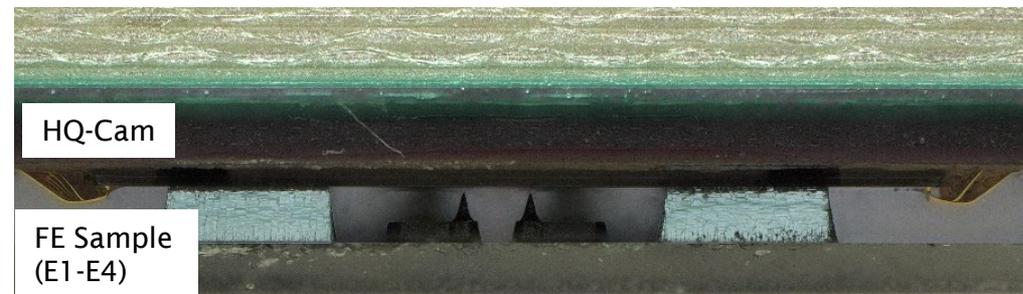
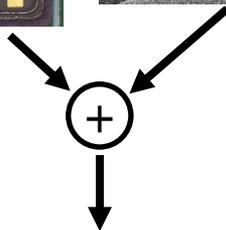
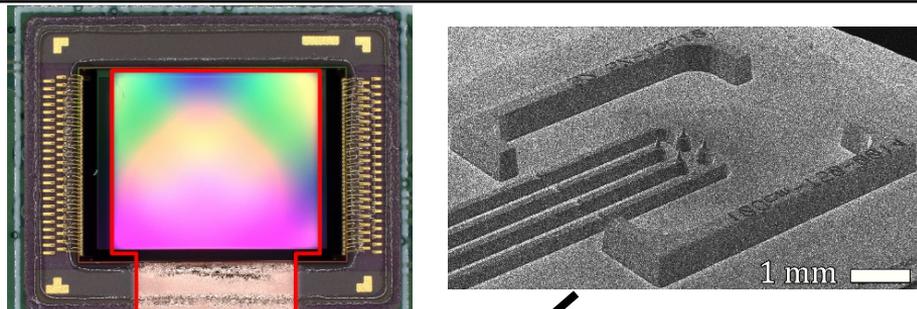
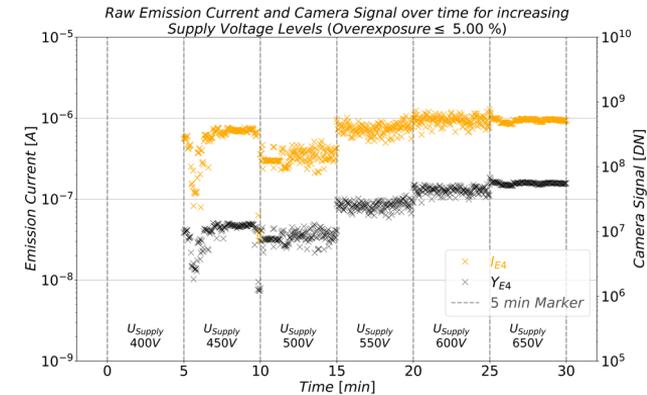
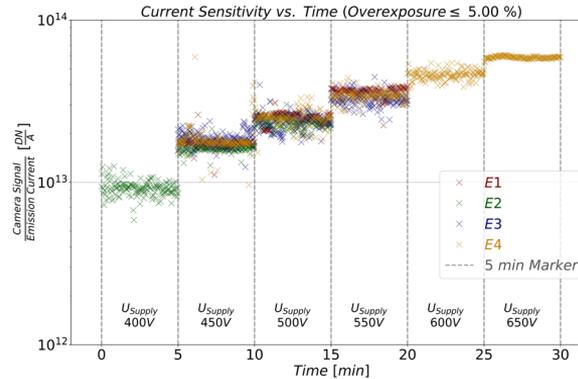
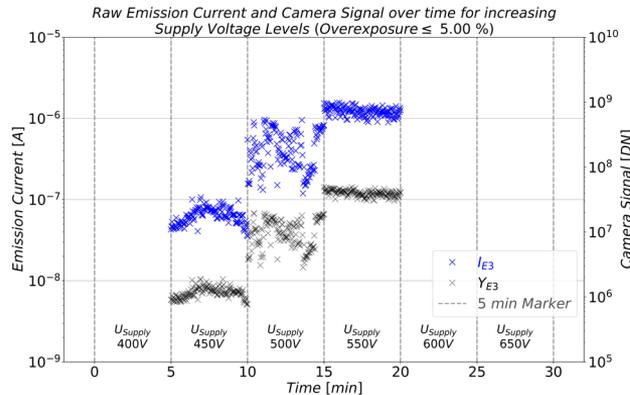
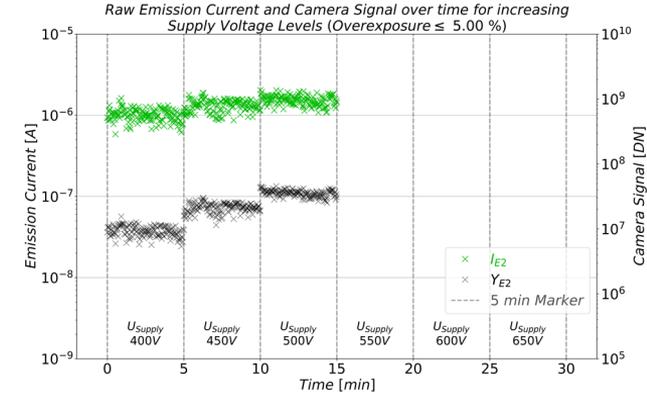
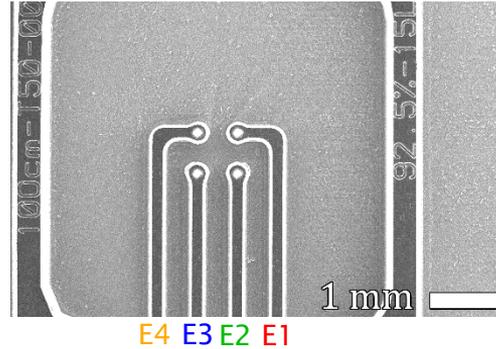
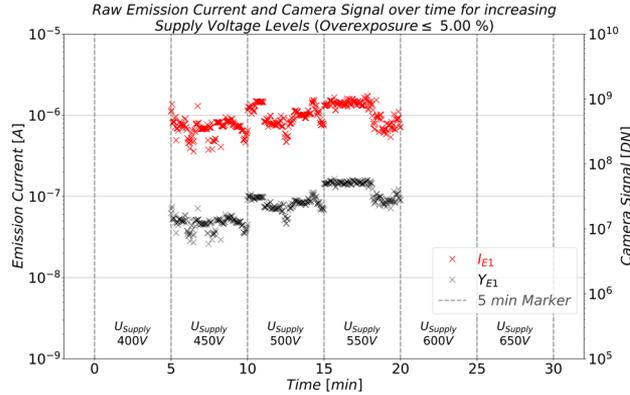


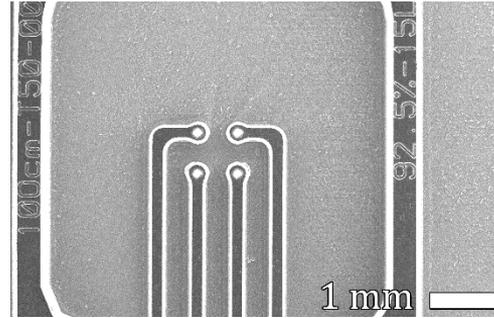
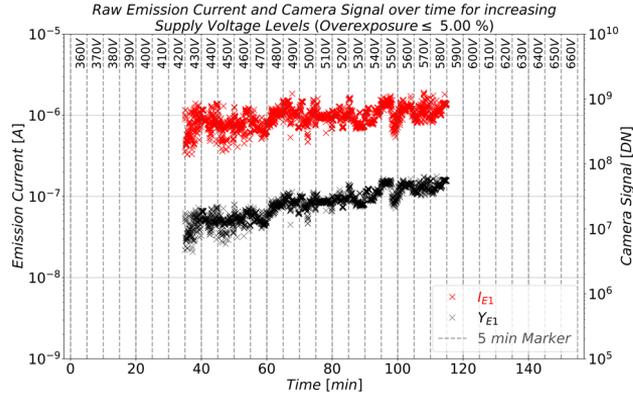
Image sensor with copper coated surface
with an light-illuminated image (coldwhite, $P_{El.}=1.5\text{ W}$),
captured by the image sensor as overlay

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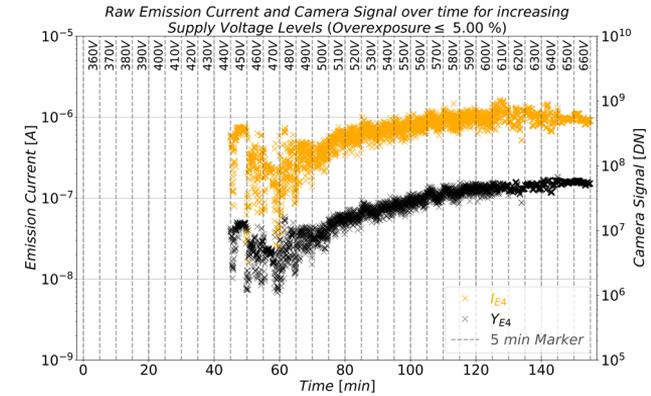
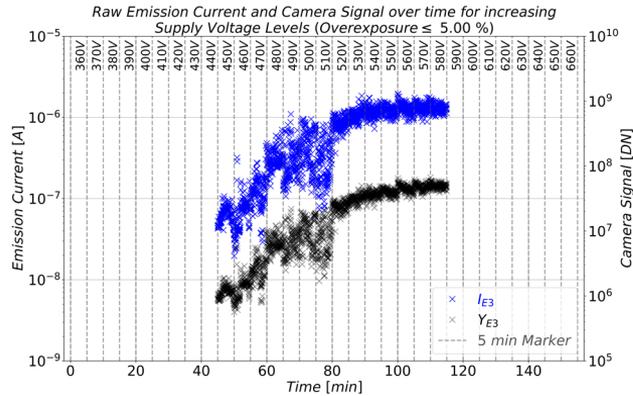
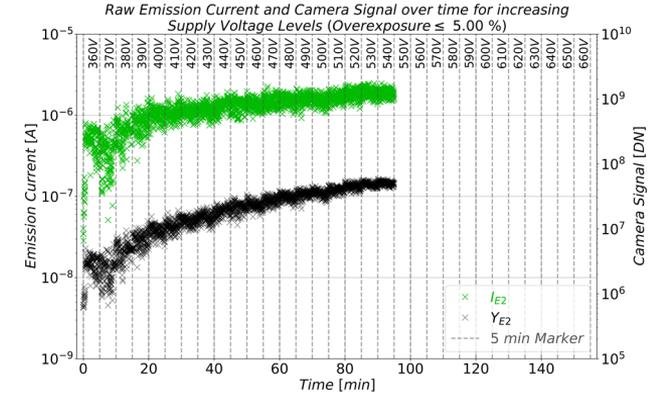
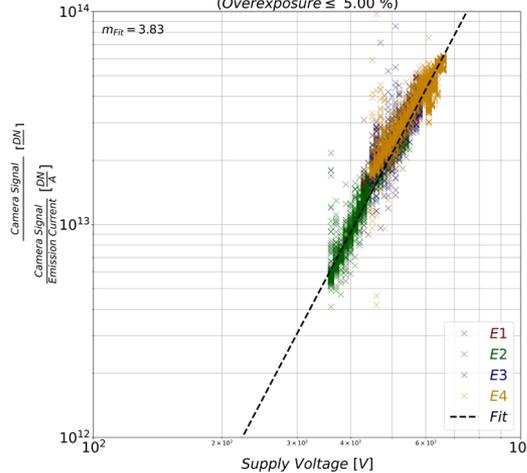


- Measured tip by tip
- Multiple supply voltages were applied to the FEA (hold for 5 minutes for statistics)
- Each current and camera signal known individually
- Used only one exposure time
→ High temporal correlation between a tips current I and its camera signal Y





Current Sensitivity vs. Supply Voltage
(Overexposure $\leq 5.00\%$)

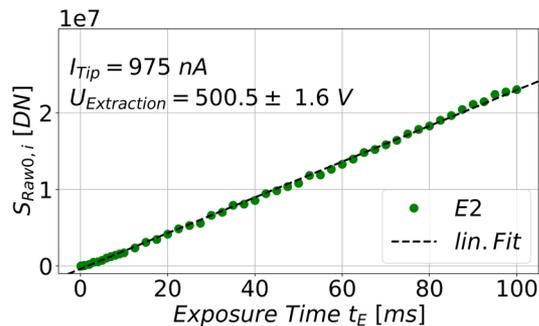


Sensitivities (Exposure Time, Current, Voltage)

Sensor signal behaves like (first approximation): $Y(t_E, I, U) \approx t_E \cdot U^b \cdot I$

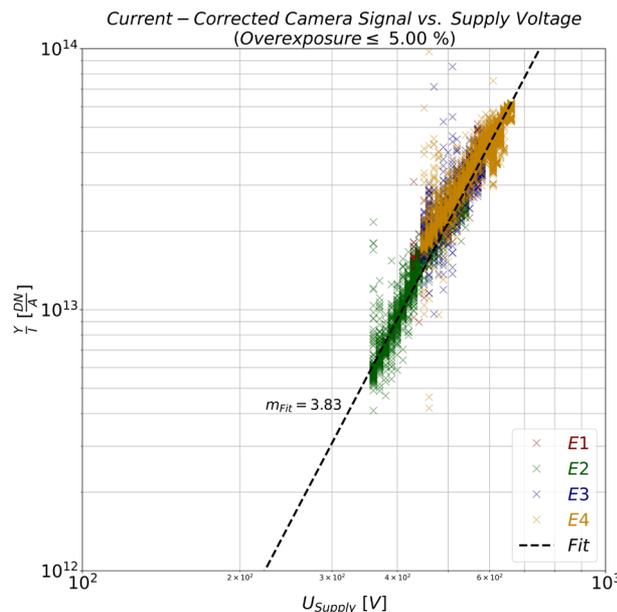
$$Y(t, I, U) \propto t_E$$

($I = \text{const.}, U \approx \text{const.}$)



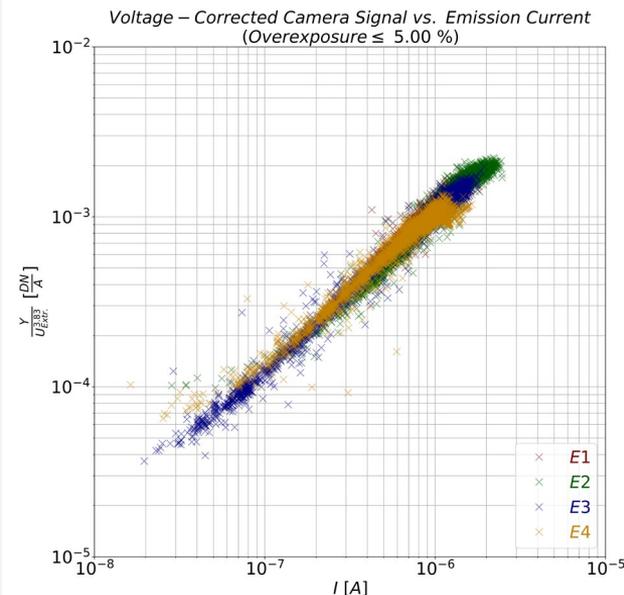
$$\frac{Y(t, I, U)}{I} \approx U^b$$

($t_E = \text{const.}$)

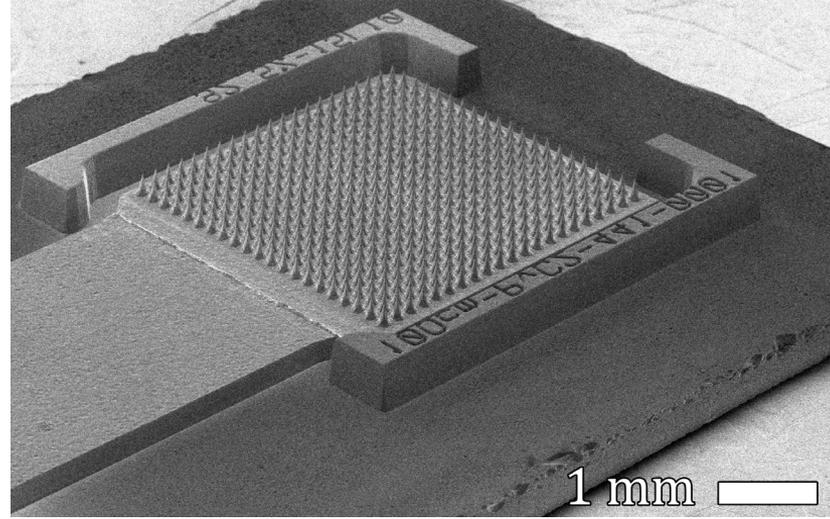
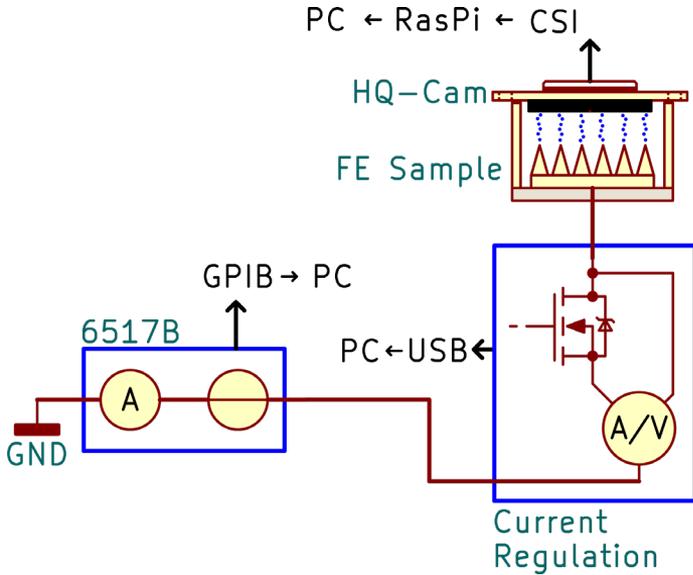


$$\frac{Y(t, I, U)}{U^b} \propto I$$

($t_E = \text{const.}$)



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Supply voltage:

1. 0V → 350V in 25V steps
 2. 350V → 700V in 5V steps
 3. 2. and 1. in reverse
- } Up-ramp
→ Downramp

Current Regulation:

- Regulation only if the cathode current would overcome a maximum set-current
→ $I_{\max} = 100\mu\text{A}$

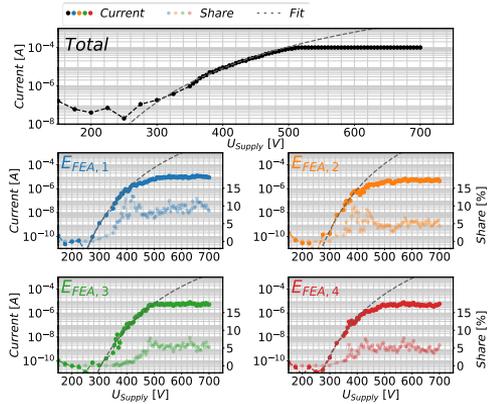
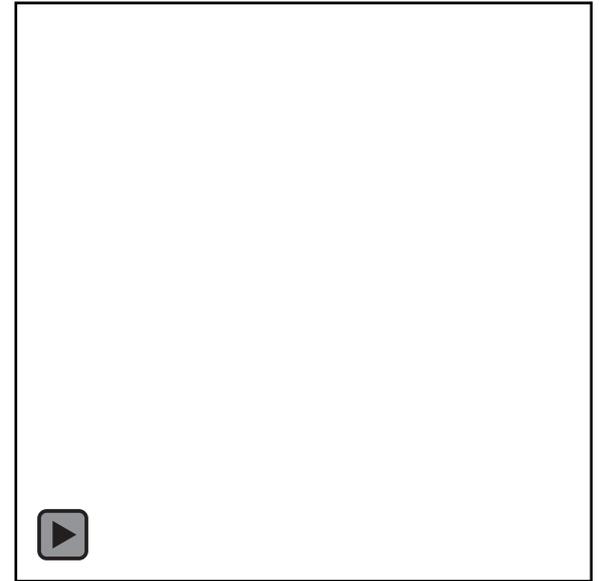
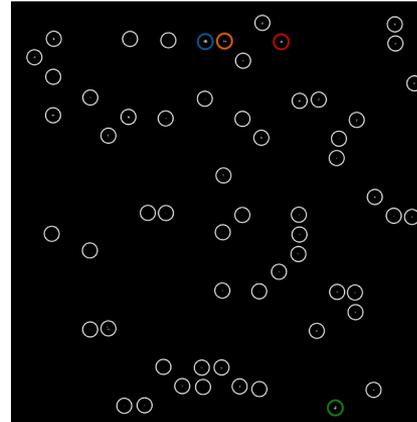
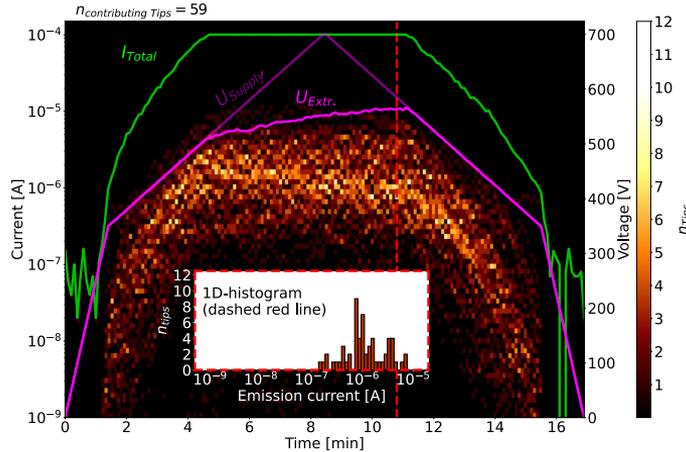


Table 2: Extracted parameters and key-values from the OMap-currents. [1]

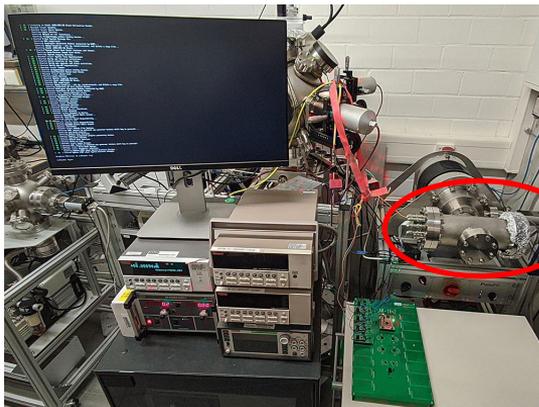
Tip [1]	Coordinate (x,y) [1] [px] [1]	Maximum-FE-Current [1] [μA] → → → ([%]) [1]	Onset-Voltage [1] [V] [1]	Field-Enhancement-Factor [1] [#] [1]
E_FEA_1 [1]	(1299,266) [1]	12.15 [1] (12.05) [1]	300 [1]	578 [1]
E_FEA_2 [1]	(1428,262) [1]	8.29 [1] (8.23) [1]	313 [1]	484 [1]
E_FEA_3 [1]	(2169,2704) [1]	8.01 [1] (8.01) [1]	343 [1]	496 [1]
E_FEA_4 [1]	(1807,267) [1]	7.85 [1] (7.77) [1]	314 [1]	532 [1]
Total-FEA [1]	- [1]	100.82 [1] (100) [1]	230 [1]	1016 [1]

Conclusions:

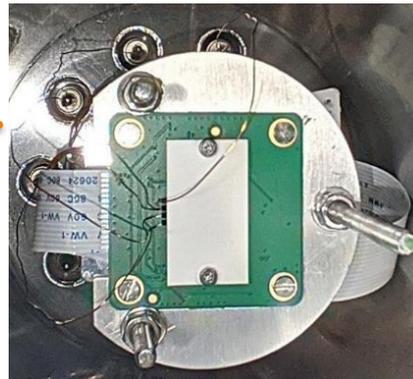
- Optical signals
 - Generated most likely by (soft) X Rays
 - reliably mappable onto the electrically measured integral FEA current
 - tips have to emit on the same potential, as the voltage has a non-linear influence
- Metallic coating
 - Far higher FE Tip currents were measurable ($> \times 20$) without damaging the lenses (increased heat dissipation)
 - No instabilities due to a conductive surface for the electrons (no feedback from charged lenses)

Outlook:

- Paper in progress about the camera system, covering
 - a detailed description of the modification process
 - the theory and influences on the measured optical camera signal
- Release of the source-code of the camera-capturing via GitHub (less effort for replication) → Stay tuned



Window view



Any
Questions?

